

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in this application.

**Listing of Claims:**

Claims 1-11 (cancelled)

12. (currently amended) A mandrel as claimed in claim ~~44~~ 22, wherein the substrate base comprises a metal ~~substrate not attacked by chemicals used in electroforming processes~~ material.

13. (currently amended) A mandrel as claimed in claim ~~44~~ 22, wherein the substrate base comprises a chrome coated glass ~~substrate~~ material.

Claims 14-21 (cancelled)

22. (new) A mandrel for use in fabricating a three dimensional electroformed structure comprising:

a substrate base;

a sacrificial controlled-release layer applied to at least one surface of the substrate base, the sacrificial controlled-release layer having an adhesive bond associated with the substrate base; and

a conductive metal layer applied to the sacrificial controlled-release layer, the conductive metal layer having a surface contactable with the three dimensional electroformed structure, the conductive metal layer having an adhesive bond associated with the three dimensional electroformed structure, the adhesive bond between the conductive metal layer and the three dimensional electroformed structure being stronger than the adhesive bond between the sacrificial controlled-release layer and the substrate base, wherein the three dimensional electroformed structure is removable from the substrate base before being removable from the conductive metal layer.

23. (new) A mandrel as claimed in claim 22, wherein the controlled-release layer comprises an organic material.

24. (new) A mandrel as claimed in claim 22, wherein the controlled-release layer comprises a material dissolvable in a solvent.

25. (new) A mandrel as claimed in claim 22, wherein the controlled-release layer comprises a material peelable from the substrate base.

26. (new) A mandrel as claimed in claim 22, the controlled-release layer comprising a brittle material, wherein the adhesive bond between the sacrificial controlled-release layer and the substrate base is fracturable.

27. (new) A mandrel as claimed in claim 26, wherein the brittle material is dissolvable in a solvent.

28. (new) A mandrel as claimed in claim 22, wherein the conductive metal layer comprises a copper material.

29. (new) A mandrel as claimed in claim 22, wherein the three dimensional electroformed structure is a printhead orifice plate.